Page 3 Dkt: 884.159US2

38. (Cancelled) The integrated circuit package of claim 37 further comprising signal traces within the dielectric layer, the signal traces being at angles other than 0, 45, and 90 degrees relative to the first and second grids of holes.

REMARKS

Applicant has carefully reviewed and considered the Office Action mailed on September 23, 2002, and the references cited therewith.

Claims 30, 35, and 37 are amended, claims 31, 32, 34, and 38 are cancelled, no new claims are added; as a result, claims 30, 35, 37, and 39-47 are now pending in this application.

Rejections Under 35 U.S.C.§112

Claims 35, 40, 44, and 47 were rejected under 35 USC § 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention.

Applicant respectfully traverses this rejection, and points out that support for these claims is present in the specification and in the Figures. Applicant further points out that amendments presented above further clarify the nature and limit the scope of the pending claims.

Attention is specifically drawn to Figures 5 and 6 which illustrate trace segments 504 and 514 rotated at an angle, and to the accompanying text on page 9, line 12 through page 10, line 23 of the specification. These descriptions and drawings illustrate how the rotated trace segments such as 504 and 514 can be rotated at other angles (arbitrary angle 610 in Figure 6), and explains the factors involved in determination of angle 610.

Rejections Under 35 U.S.C.§102

Claims 30-32, 34, 35, 39, 40, and 42-44 were rejected under 35 U.S.C.§102(b) as being anticipated by Duxbury (U.S. Patent No. 5,360,949).

Duxbury describes a printed circuit board in which pairs of conductive wires are supported by a flexible nonconductive sheet which is placed between two conductive ground

CHIP PACKAGE WITH DEGASSING HOLES

meshes. The angle that the conductive wire traces take relative to the orientation of the conductive mesh is selected to vary the offset of mesh interconnection points from the conductive wires. The application further discusses that it may be adapted to a multilayer printed circuit board, and that the ground mesh may be replaced with a plurality of holes in the form of a matrix.

Duxbury does not teach an integrated circuit package, and does not teach offsetting a second conductive layer having a second grid of holes from a first conductive layer having a first grid of holes. The description of Duxbury's Figure 4 clearly recites that "the upper mesh conductors 36 are parallel to the lower mesh conductors 38" (see, col. 4, ln. 36-37). Duxbury does recite that a mesh may in another embodiment be a conductive sheet with a plurality of holes as shown in Figure 7, but fails to consider degassing holes disposed within an integrated circuit package as are recited in claim 39 and its dependents.

Duxbury also fails to consider disposing its various elements in accordance with the relative coordinate systems now present in the amended claim 30 and its dependents.

For these reasons, applicant believes the claims as amended are in condition for allowance, and respectfully requests reexamination and allowance of the pending claims.

Rejections Under 35 U.S.C.§103

Claims 37, 41, and 45-47 were rejected under 35 U.S.C.§103(a) as being unpatentable over Duxbury (U.S. Patent No. 5,360,949) as applied to claims 30-32, 34, 35, 39, 40, and 42-44, and further in combination with Tanahashi (U.S. Patent No. 6,184,477).

Applicant believes that the discussion presented above in combination with the amendments to the claims are further applicable here, and incorporates the above discussion by reference. Further, because these claims depend from base claims believed to be in condition for allowance, they are believed to be allowable as based on an allowable base claim

For these reasons, reexamination and allowance of these claims is respectfully requested.

Filing Date: March 7, 2001
Title: CHIP PACKAGE WITH DEGASSING HOLES

Page 5 Dkt: 884.159US2

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney (612) 349-9581 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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CERTIFICATE UNDER 37 CFR 1.8: The undersign	ed hereby certifies that this correspondence is being deposited with the United States	Postal
Service with sufficient postage as first class mail, in a	an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this	S
day of January, 2003.		

	CHAL JUGGS
Jane Sagers	
Name	Signature (/